

### Part Number: XZMDKCBD45S

3.5x2.8mm PLCC4 SMD LED

### **Features**

• Ideal for indication light on hand held products

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- Long life and robust package
- Variety of lens types and color choices available
- ullet Package: 1500pcs / reel
- Moisture sensitivity level : level 3
- RoHS compliant



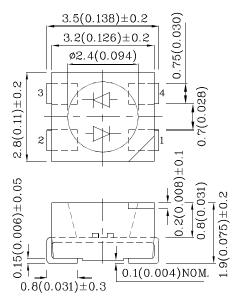




# ATTENTION OBSERVE PRECAUTIONS

SERVE PRECAUTION
FOR HANDLING
ELECTROSTATIC
DISCHARGE
SENSITIVE
DEVICES

### **Package Schematics**



CBD 3 ⊶ 4

MDK 2 ⊶>→ 1

### Notes:

- 1. All dimensions are in millimeters (inches).
- 2. Tolerance is  $\pm 0.25(0.01")$  unless otherwise noted.
- 3. Specifications are subject to change without notice.

Absolute Maximum Ratings (T <sub>A</sub> =25°C)		MDK (AlGaInP)	CBD (InGaN)	Unit
Reverse Voltage	$V_{\mathrm{R}}$	5	5	V
Forward Current	$I_{\mathrm{F}}$	30	30	mA
Forward Current (Peak) 1/10 Duty Cycle 0.1ms Pulse Width	ifs	185	150	mA
Power Dissipation	$P_{D}$	75	120	mW
Electrostatic Discharge Threshold (HBM)		-	250	V
Operating Temperature	$T_{\rm A}$	-40 ~ +85		°C
Storage Temperature	Tstg	-40 ~ +85		

Operating Characteristics (T <sub>A</sub> =25°C)		MDK (AlGaInP)	CBD (InGaN)	Unit
Forward Voltage (Typ.) (I <sub>F</sub> =20mA)	$V_{\mathrm{F}}$	1.95	3.3	V
Forward Voltage (Max.) (I <sub>F</sub> =20mA)	$V_{\mathrm{F}}$	2.5	4	V
Reverse Current (Max.) $(V_R=5V)$	$I_R$	10	50	uA
Wavelength of Peak Emission (Typ.) (I <sub>F</sub> =20mA)	λP	650	468	nm
Wavelength of Dominant Emission (Typ.) (I <sub>F</sub> =20mA)	λD	630	470	nm
Spectral Line Full Width At Half-Maximum (Typ.) (I <sub>F</sub> =20mA)	Δλ	28	25	nm
Capacitance (Typ.) (V <sub>F</sub> =0V, f=1MHz)	С	35	100	pF

Part Number	Emitting Color	Emitting Material	Lens-color	$\begin{array}{c} Luminous\\ Intensity\\ (I_F=20mA)\\ mcd \end{array}$		Wavelength nm λΡ	Viewing Angle 20 1/2
				min.	typ.		
XZMDKCBD45S —	Red	AlGaInP	W. J. Cl.	200	317	650	120°
	Blue	InGaN	- Water Clear	70	128	468	

Apr 18,2011 XDSB5016 V2 Layout: Maggie L.

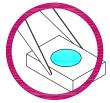
### **Handling Precautions**

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Compare to epoxy encapsulant that is hard and brittle, silicone is softer and flexible. Although its characteristic significantly reduces thermal stress, it is more susceptible to damage by external mechanical force.

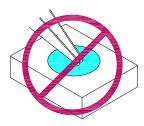
As a result, special handling precautions need to be observed during assembly using silicone encapsulated LED products. Failure to comply might lead to damage and premature failure of the LED.

1. Handle the component along the side surfaces by using forceps or appropriate tools.

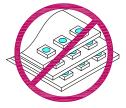


2. Do not directly touch or handle the silicone lens surface. It may damage the internal circuitry.

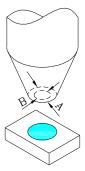




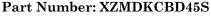
3. Do not stack together assembled PCBs containing exposed LEDs. Impact may scratch the silicone lens or damage the internal circuitry.



- 4.1. The outer diameter of the SMD pickup nozzle should not exceed the size of the LED to prevent air leaks. The inner diameter of the nozzle should be as large as possible.
- 4.2. A pliable material is suggested for the nozzle tip to avoid scratching or damaging the LED surface during pickup.
- 4.3. The dimensions of the component must be accurately programmed in the pick-and-place machine to insure precise pickup and avoid damage during production.

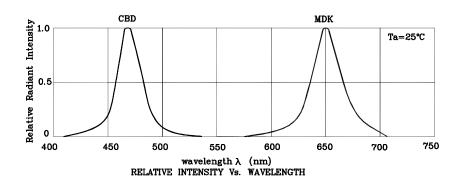


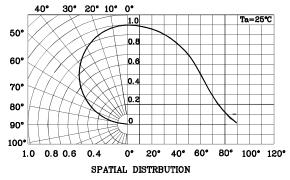
5. As silicone encapsulation is permeable to gases, some corrosive substances such as  $H_2S$  might corrode silver plating of lead-frame. Special care should be taken if an LED with silicone encapsulation is to be used near such substances.



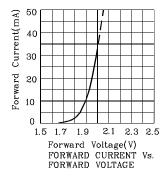


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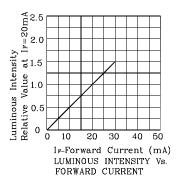


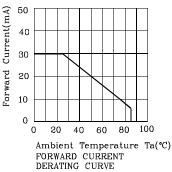


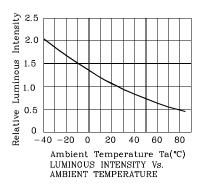
### **❖** MDK



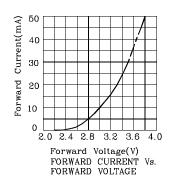
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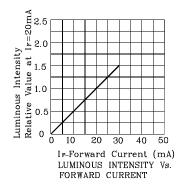


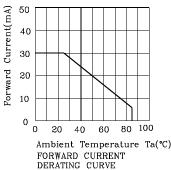


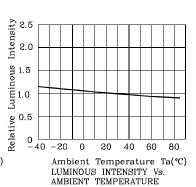


### **♦** CBD









Apr 18,2011

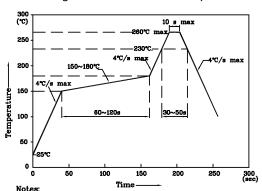
XDSB5016 V2 Layout: Maggie L.



3.5x2.8mm PLCC4 SMD LED

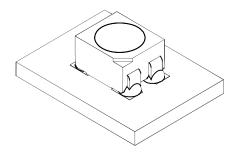
# LED is recommended for reflow soldering and soldering profile is shown below.

Reflow Soldering Profile for SMD Products (Pb-Free Components)

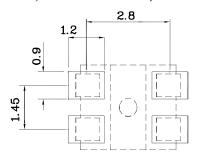


- 1. Maximum soldering temperature should not exceed 260°C
- 2. Recommended reflow temperature: 145°C-260°C
- 3. Do not put stress to the epoxy resin during high temperatures conditions

❖ The device has a single mounting surface. The device must be mounted according to the specifications.



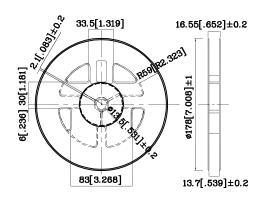
**♦** Recommended Soldering Pattern (Units: mm; Tolerance: ± 0.1)



## **❖** Tape Specification (Units:mm)

# TAPE 4.0±0.1 2.0±0.1 4.0±0.1 91.5±0.1 2.15±0.1 4 1 3 2

# \* Reel Dimension



### Remarks:

If special sorting is required (e.g. binning based on forward voltage, Luminous intensity / luminous flux, or wavelength), the typical accuracy of the sorting process is as follows:

- 1. Wavelength: +/-1nm
- 2. Luminous intensity / luminous flux: +/-15%
- 3. Forward Voltage: +/-0.1V

Note: Accuracy may depend on the sorting parameters.

XDSB5016 V2 Layout: Maggie L.





### PACKING & LABEL SPECIFICATIONS

